



## Product/Process Change Notice - PCN 12\_0255 Rev. A

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This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

*Note: Revised fields are indicated by a red field name. See Appendix B for revision history.*

**PCN Title:** ADuC7039 Metal Mask Edit resulting in Product Improvements, and Assembly Site Change

**Publication Date:** 20-Feb-2013

**Effectivity Date:** 21-May-2013 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Add change to Assembly Mold Compound and Die Attach material

### Description Of Change

- 1) ADuC7039 Metal mask edit resulting in improvement to the LIN fault Collision error detection, Flash Iprog, VCO and IDDQ.
- 2) Change assembly to STATSChipPAC Malaysia (SCM) from AMKOR, Philippines.
- 3) The assembly transfer will result in a change to one of the die attach materials from Ablestik 8290 to Ablestik 3230 and mold compound will change from Sumitomo G700 to Sumitomo G770. Both these materials are fully qualified and have been in use by ADI for some time.

### Reason For Change

- 1) Metal mask improvements as requested by the customer.
- 2) Consolidate assembly in SCM.

### Impact of the change (positive or negative) on fit, form, function & reliability

The change in assembly location and improvements for LIN Fault Collision error detection, Flash Iprog, VCO and IDDQ will not impact the device form, fit, function, quality or reliability of the ADuC7039.

ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

### Product Identification *(this section will describe how to identify the changed material)*

The above improvements will be incorporated in the ADuC7039WBCPZ and ADuC7039WBCPZ-RL which is branded as follows:

Line 1: ADUC7039

Line 2: WBCPZ

Line 3: D60 # DATECODE

Line 4: ASSEMBLY LOT NUMBER

Line 5: COUNTRY OF ORIGIN

### Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

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**Supporting Documents**

**Attachment 1:** Type: Qualification Report Summary

ADI\_PCN\_12\_0255\_Rev\_A\_ADuC7039 Qualification Results.pdf

**For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative**

**Americas:** [PCN\\_Americas@analog.com](mailto:PCN_Americas@analog.com)

**Europe:** [PCN\\_Europe@analog.com](mailto:PCN_Europe@analog.com)

**Japan:** [PCN\\_Japan@analog.com](mailto:PCN_Japan@analog.com)

**Rest of Asia:** [PCN\\_ROA@analog.com](mailto:PCN_ROA@analog.com)

**Appendix A - Affected ADI Models**

**Existing Parts - Product Family / Model Number (2)**

ADUC7039 / ADUC7039BCP6Z

ADUC7039 / ADUC7039BCP6Z-RL

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	05-Dec-2012	05-Mar-2013	Initial Release
Rev. A	20-Feb-2013	21-May-2013	Add change to Assembly Mold Compound and Die Attach material

Analog Devices, Inc.

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